

SHIMIZU et al., S.N. 09/406,570

Dkt. 2271/57219-A

Exhibit C

(substitute drawings - Figs. 1A-18B)

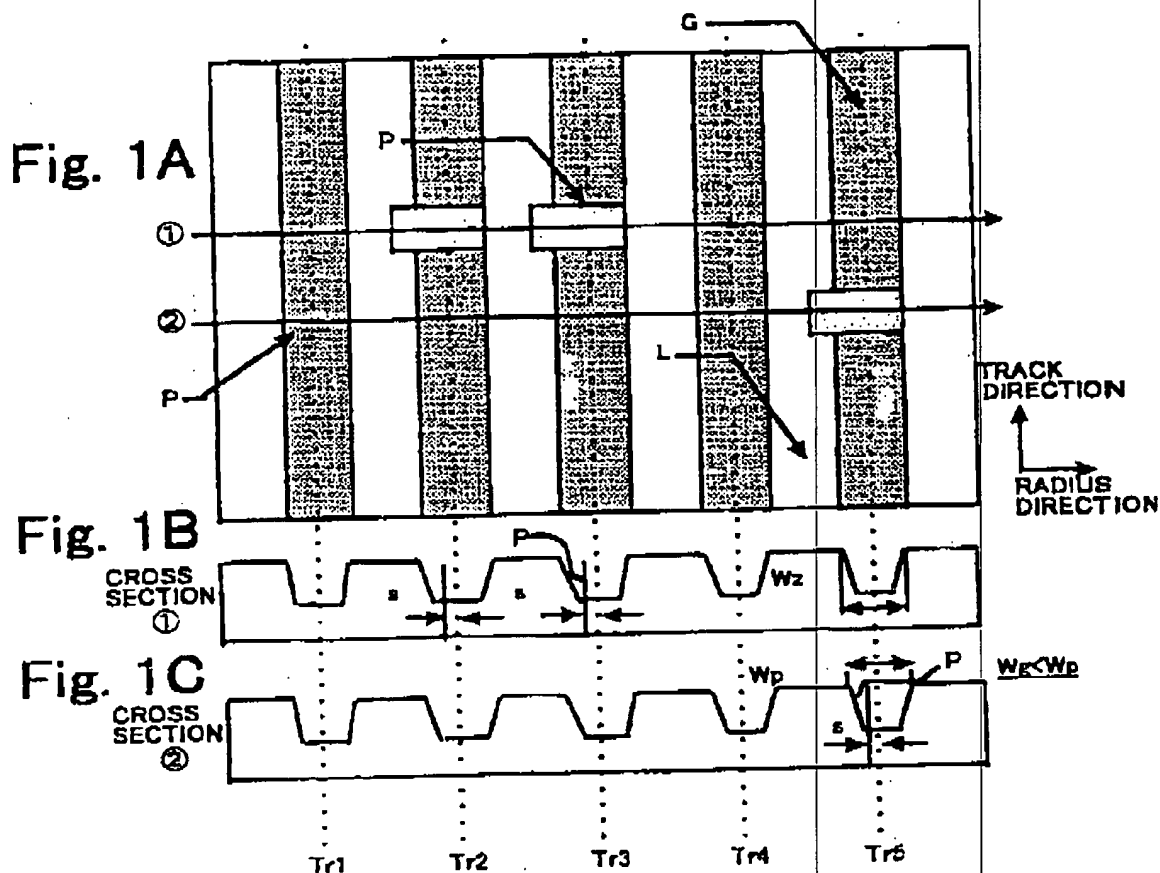


Fig. 2A

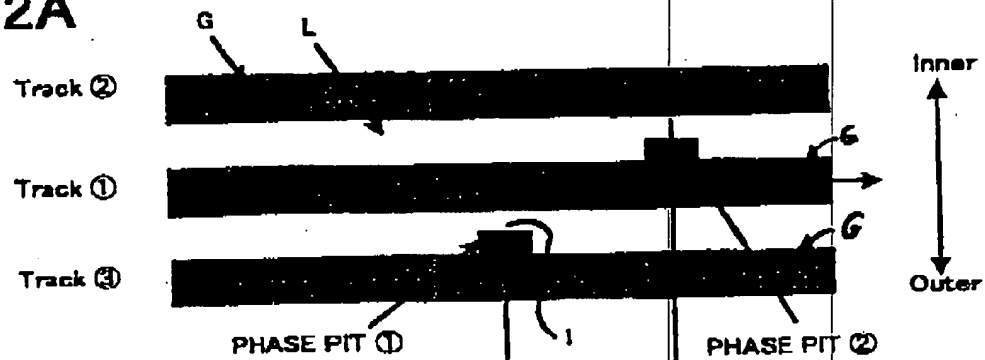


Fig. 2B

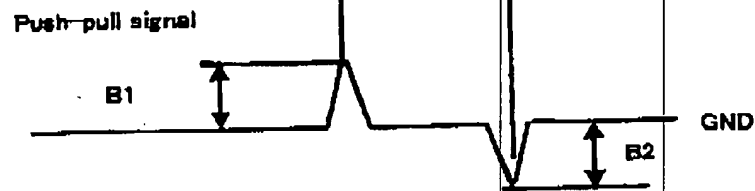


Fig. 3

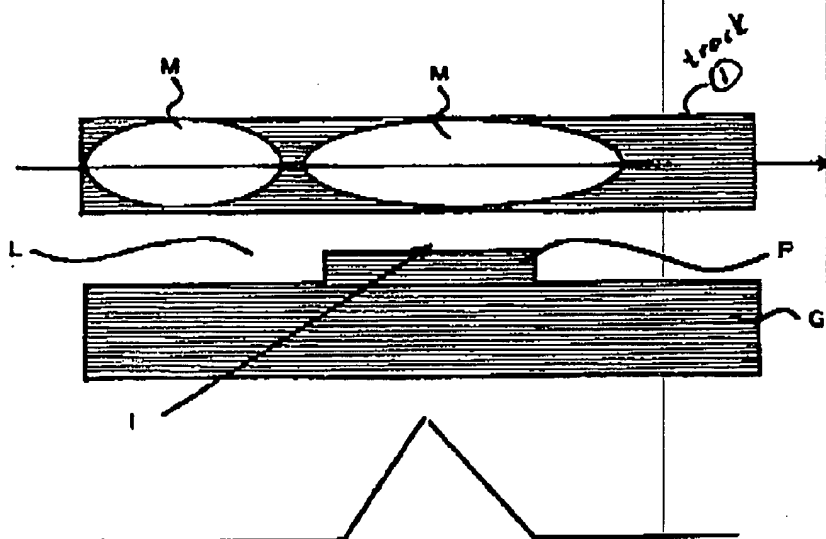


Fig. 4

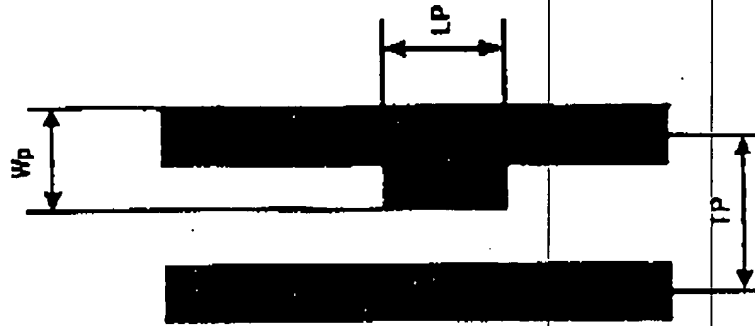
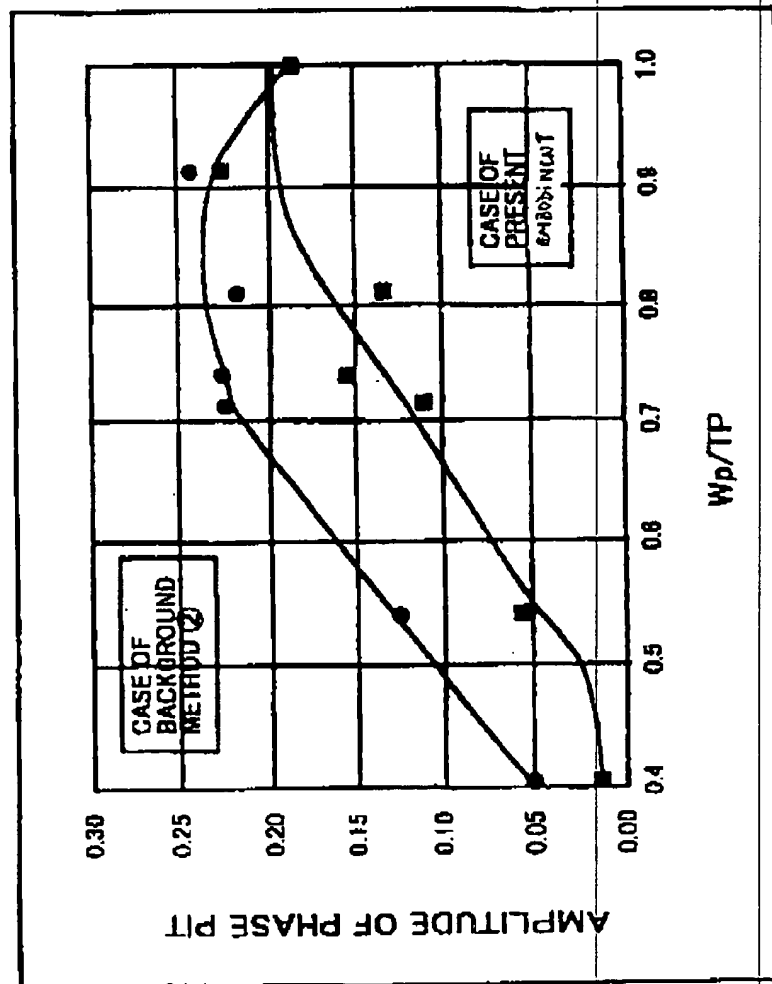


Fig. 5

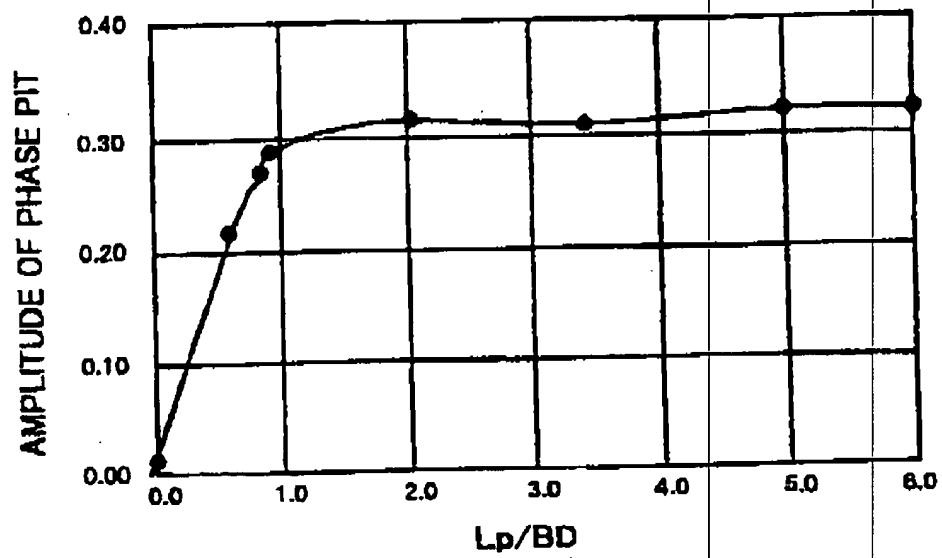


Fig. 6A

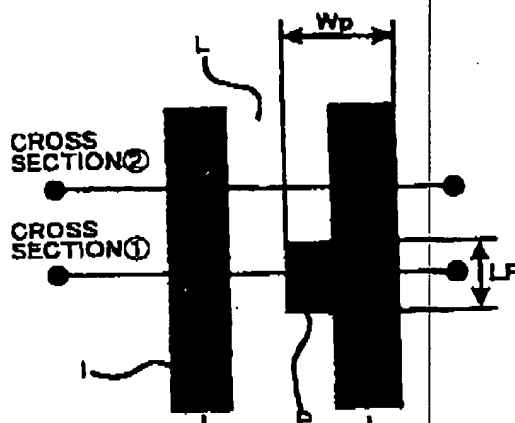


Fig. 6B



Fig. 6C

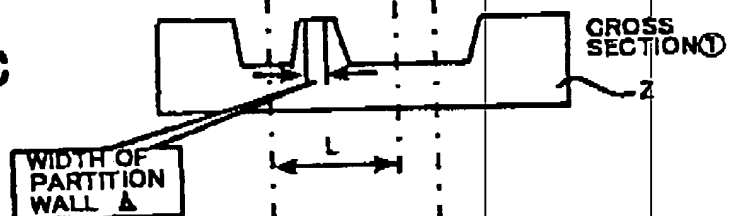


Fig. 6D

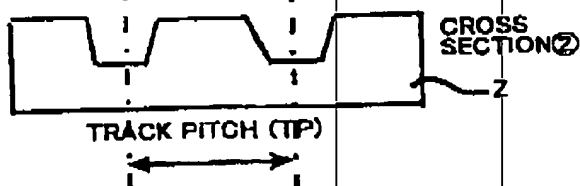


Fig. 7

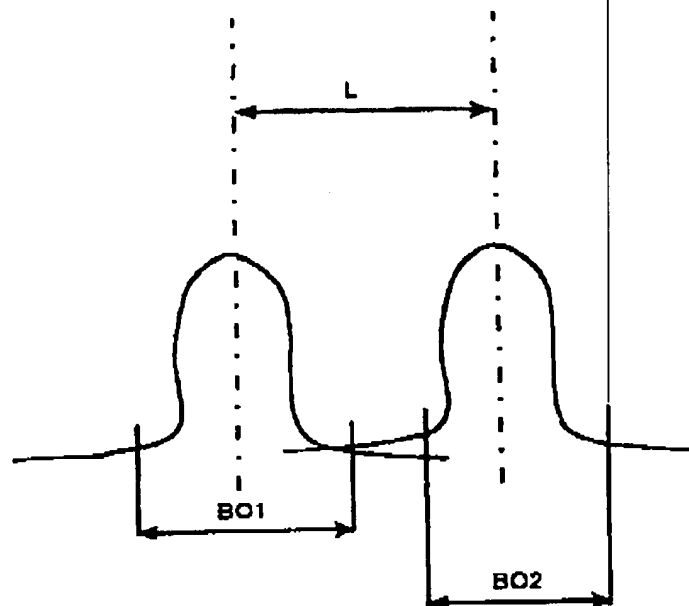


Fig. 9A

MAKING OF RESIST
ORIGINAL BOARD

Fig. 9B

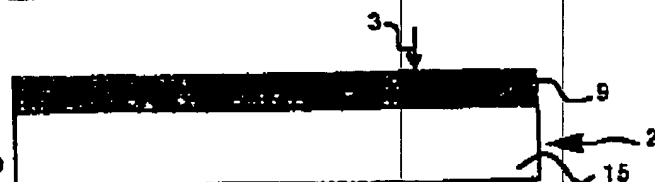
EXPOSING OF
ORIGINAL BOARD

Fig. 9C

DEVELOPING

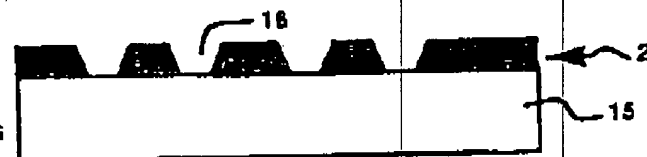


Fig. 9D

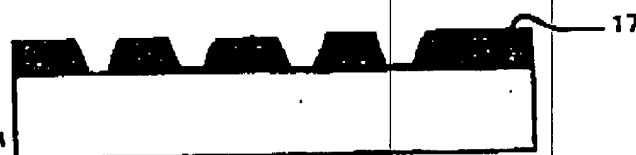
PROCESSING OF
CONDUCTIVE FILM

Fig. 9E

Ni ELECTROFORMING

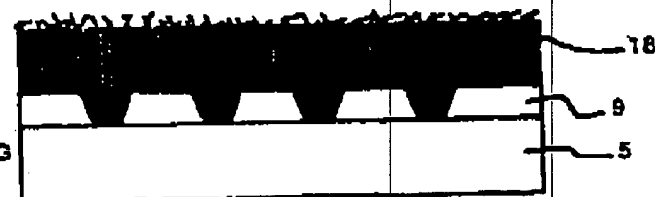
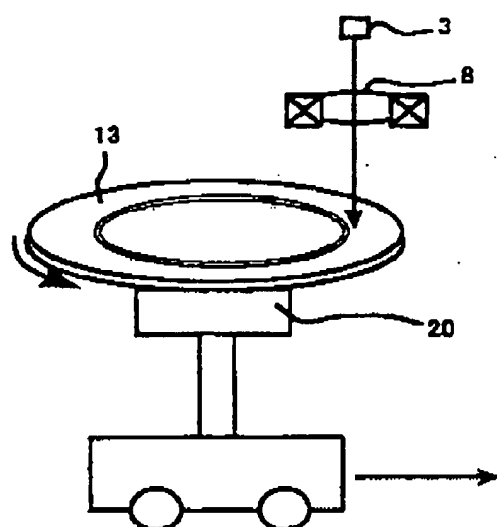


Fig. 9F

REELING-OFF · CLEANING ·
POLISHING OF REAR SURFACE ·
FINAL PROCESSING

Fig. 10



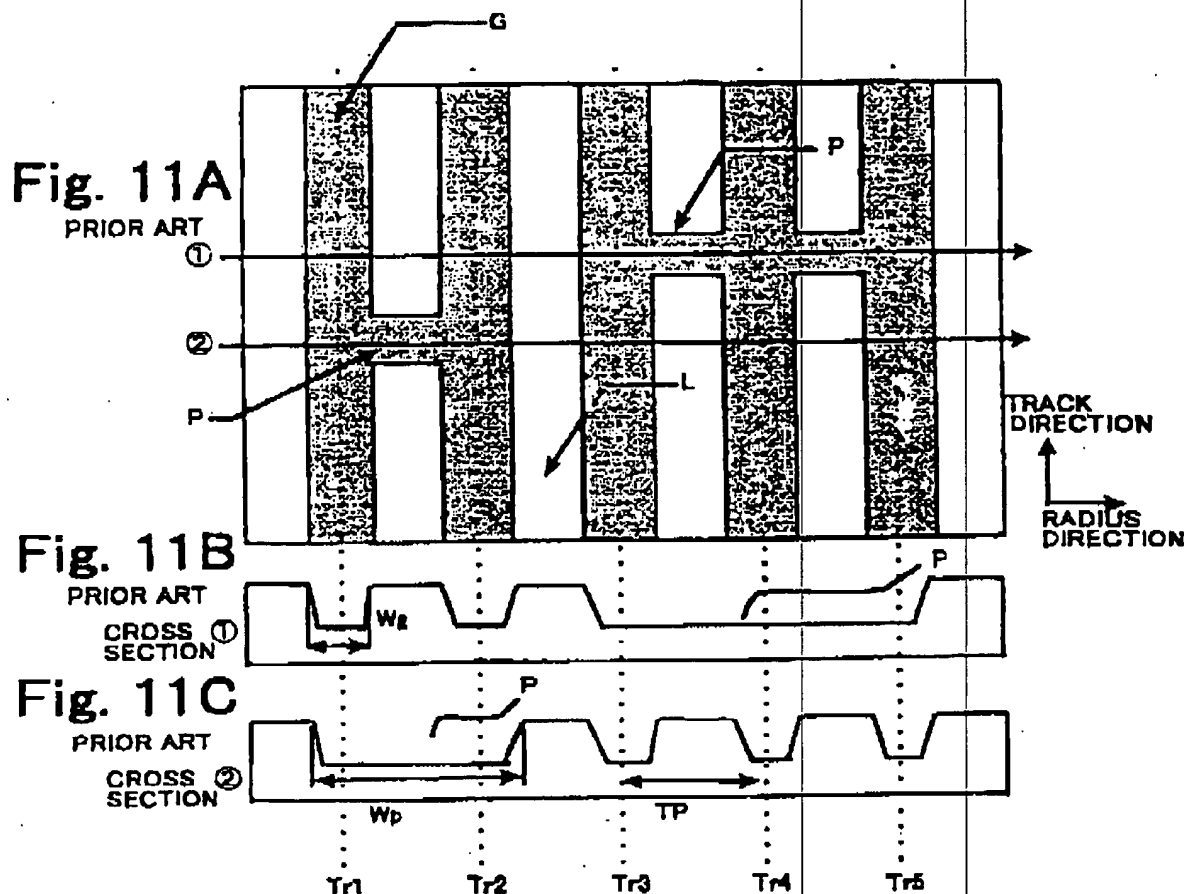


Fig. 12A

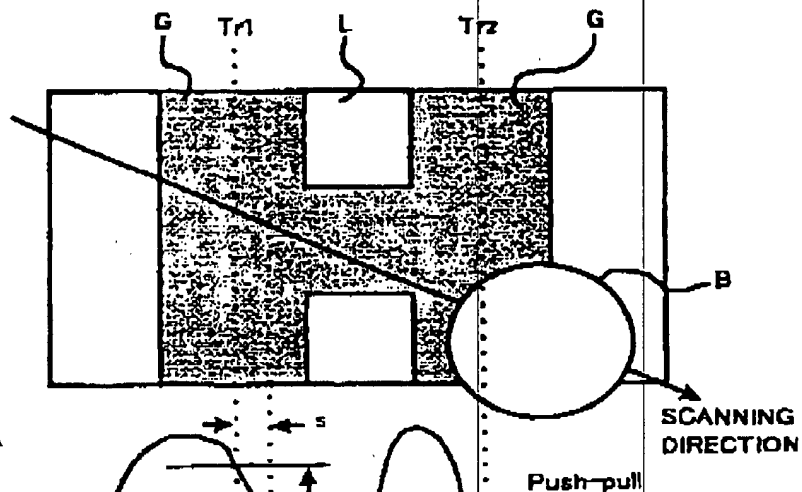


Fig. 12B

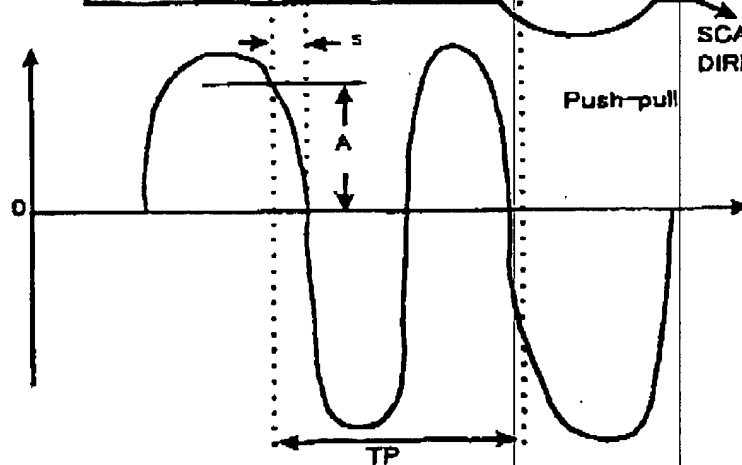


Fig. 13A

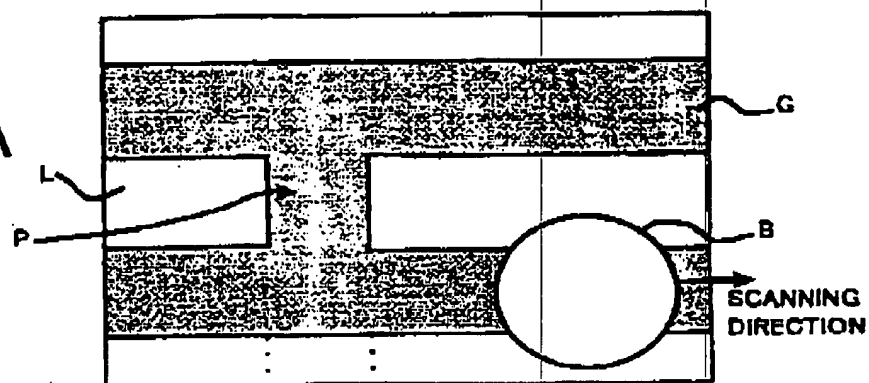


Fig. 13B

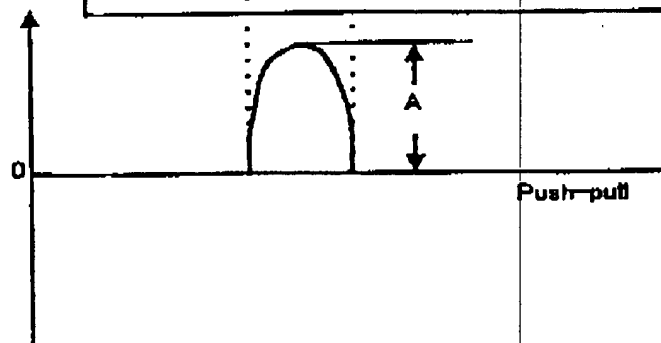


Fig. 14A

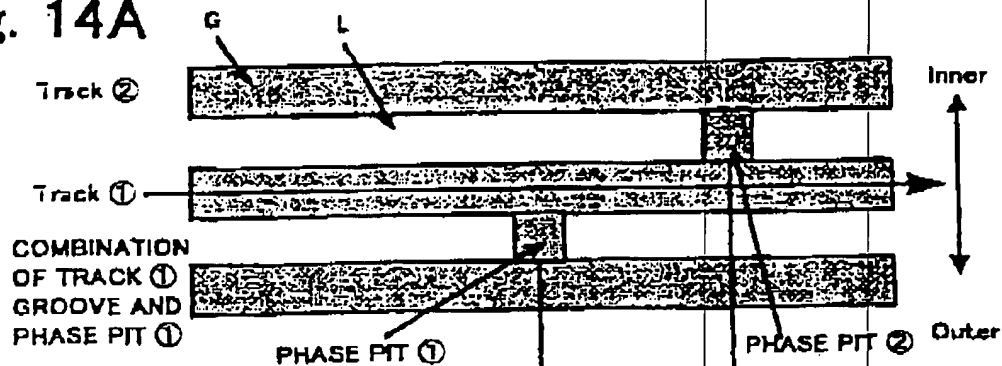


Fig. 14B

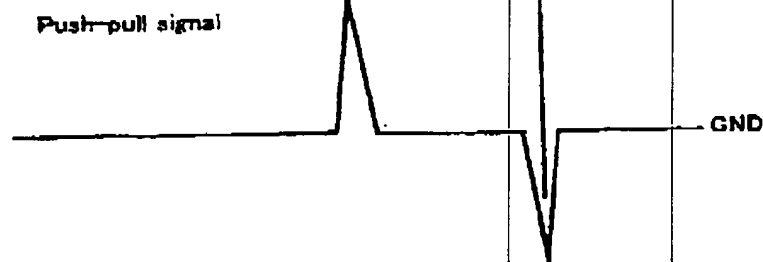


Fig. 15A

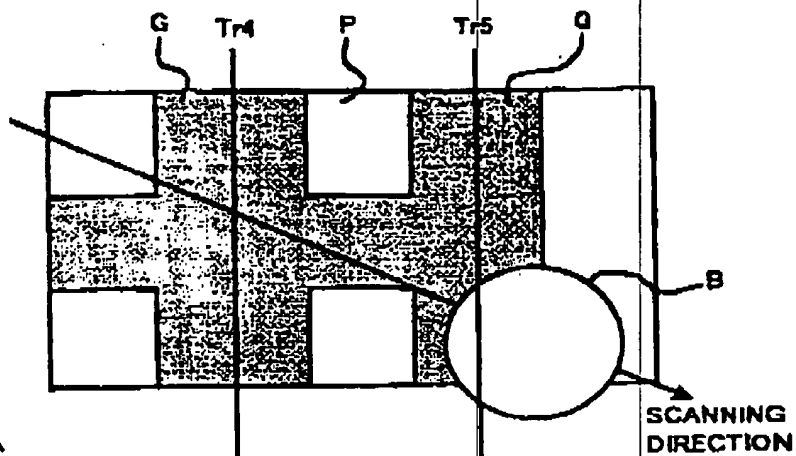


Fig. 15B

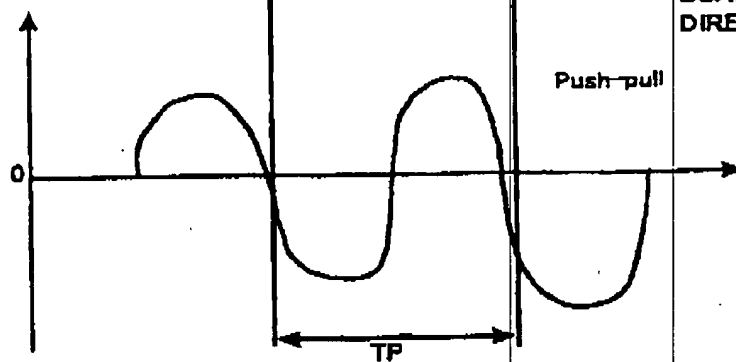


Fig. 16A

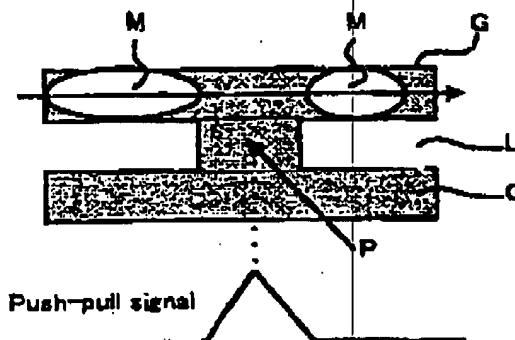


Fig. 16B

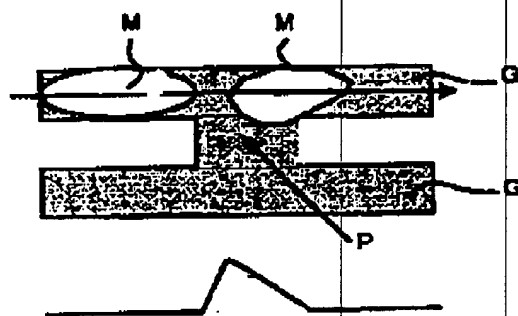


Fig. 16C

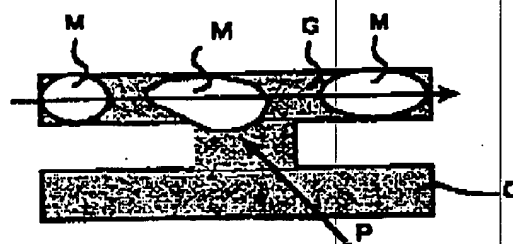
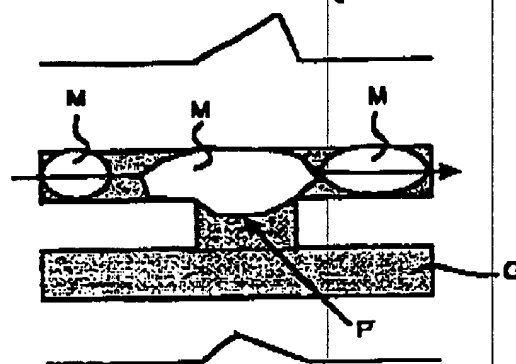


Fig. 16D



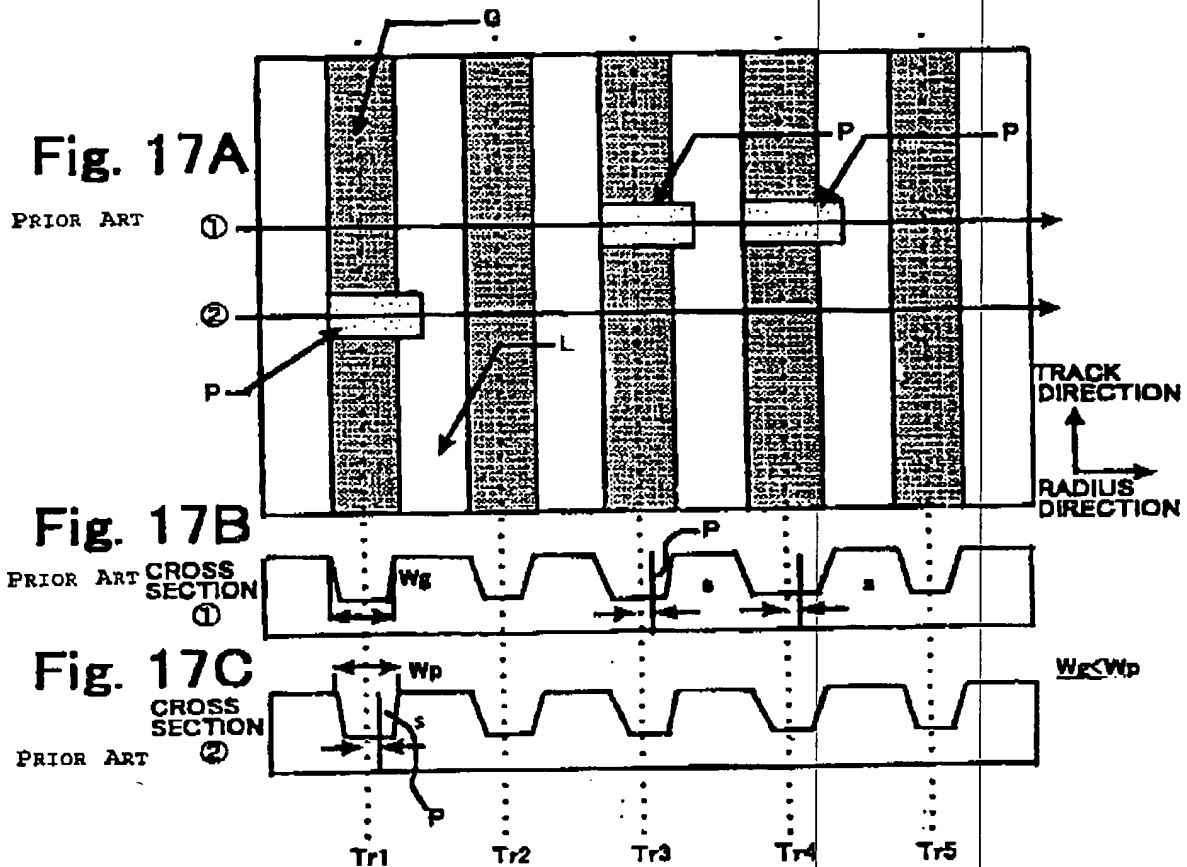


Fig. 18A

PRIOR ART

Track ②

Track ①

COMBINATION
OF TRACK ①
GROOVE AND
PHASE PIT ①

PHASE PIT ①

PHASE PIT ②

Inner

Outer

Push-pull signal

Fig. 18B

PRIOR ART

A1

GND

A2